

## **Abstract**

A package array and its package unit of flip chip LED are proposed, wherein an LED chip is mounted on a ceramic material capable of enduring the eutectic temperature of the fabrication process for packaging. Next, metal wires are  
5 directly distributed on the ceramic material to finish an LED package unit, or a plurality of LEDs are serial/parallel connected with metal wires on the ceramic material to finish a high density package array. Because the ceramic material has a good thermal expansion match and a good thermal conductivity and the LED chip itself has a high reflective index match, the light emission  
10 characteristic and heat-radiating effect of the packaged LED can be effectively improved.